ANGLES

1. All resistance values are in Ohms, 0.1 Watt +/- 5%.
2. All capacitance values are in microfarads.
3. All crystal & oscillator values are in hertz.

DIMENSIONS ARE IN MILLIMETERS

TITLED PAGE AND CONTENTS

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BUBBA
DVT BUILD
11/20/2002

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# PCB Specs

**Thickness:** 1.2 mm / 0.047 in  
1/2 oz Cu thickness: 0.7 mils  
1.0 oz Cu thickness: 1.4 mils  

**Impedance:** 50 ohms +/- 10%  
**Dielectric:** FR-4  
**Layer Count:** 12  
**Signal Trace Width:** 4 mils  
**Signal Trace Spacing:** 4 mils  
**Prepreg Thickness:** 2-3 mils  

See PCB CAD files for more specific info.

## Board Stack-up and Construction

<table>
<thead>
<tr>
<th>Layer</th>
<th>Material/Trace</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td><strong>Signal (1/3 oz + Copper Plating)</strong></td>
</tr>
<tr>
<td>2</td>
<td><strong>Prepreg (3mil)</strong></td>
</tr>
</tbody>
</table>
| 3     | **Laminate (4mil)**  
**Signal (1/2 oz)** |
| 4     | **Prepreg (3mil)**  
**Signal (1/2 oz)** |
| 5     | **Laminate (4mil)**  
**Ground (1/2 oz)** |
| 6     | **Prepreg (2mil)**  
**Cut Power Plane (1 oz)** |
| 7     | **Laminate (3mil)**  
**Cut Power Plane (1 oz)** |
| 8     | **Prepreg (2mil)**  
**Ground (1/2 oz)** |
| 9     | **Laminate (4mil)**  
**Signal (1/2 oz)** |
| 10    | **Prepreg (3mil)**  
**Signal (1/2 oz)** |
| 11    | **Laminate (4mil)**  
**Ground (1/2 oz)** |
| 12    | **Prepreg (3mil)**  
**Signal (1/3 oz + Copper Plating)** |

**Dielectric:** FR-4  
**Thickness:** 1.2 mm / 0.047 in  
1/2 oz Cu thickness: 0.7 mils  
1.0 oz Cu thickness: 1.4 mils  
**Impedance:** 50 ohms +/- 10%  
**Layer Count:** 12  
**Signal Trace Width:** 4 mils  
**Signal Trace Spacing:** 4 mils  
**Prepreg Thickness:** 2-3 mils  

See PCB CAD files for more specific info.
RIGHT USB PORT

PUT R6, R7 AND L2 ACROSS THE MOAT

USB CONNECTOR

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+5V_USB_VDD

USB_D2P

USB_D2M

USB_D2P_EMI

USB_D2M_EMI

USB_D2P

USB_D2M

USB_D2P_EMI

USB_D2M_EMI